## TELEFUNKEN ELECTRONIC

17E D ■ 8920096 0009739 1 ■ALGG

# **BAW 24...BAW 27**

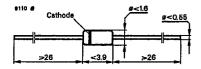
TELEFUNKEN electronic
Creative Technologies

## **Silicon Epitaxial Planar Diodes**

T-03-09

Applications: High speed switch in core memory

Dimensions in mm



Standard glass case 54A2 DIN 41 880 JEDEC DO 35 Weight max. 0.15 g

Marking: By letters

Absolute maximum ratings				
Repetitive peak reverse voltage				
	BAW 24 · BAW 25	$V_{ m RRM}$	50	٧
	BAW 26 · BAW 27	V <sub>RRM</sub>	75	V
Reverse voltage				
	BAW 24 · BAW 25	$V_{R}$	40	٧
	BAW 26 · BAW 27	$V_{R}$	60	V
Surge forward current				
$t_p = 1  \mu s$		I <sub>FSM</sub>	4	Α
Forward current		I <sub>F</sub>	600	mA
Average forward current				
$V_{\rm R} = 0$		I <sub>FAV</sub>	300	mA
Power dissipation				
I = 4 mm, T <sub>L</sub> = 45 °C		$P_{V}$	440	mW
<i>T</i> <sub>L</sub> ≤ 25 °C		P <sub>V</sub> P <sub>V</sub>	500	mW
Junction temperature		$\tau_{\mathbf{j}}$	200	<b>℃</b>
Storage temperature range		$T_{\mathrm{stg}}$	- 65+ 200	<b>℃</b>
Maximum thermal resistance				
Junction ambient				
$l=4$ mm, $T_L = constant$		R <sub>thJA</sub>	350	K/W

T1.2/912.0588 E

3800 F-01

29

BAW 24...BAW 27

T-03-09

9.41-	Tym	Max.	
(Alifir	· yp.		
F	8.0	0.9	V
; F	0.67		٧
	0.92		٧
; F	0.8		V
; £	1,05		٧
; F	0.95		V
; F	1.12	1.25	٧
		400	-4
ł			nA nA
3		100	NΑ
1			μA
1		50	μА
=0			v
(BR)			v
/ <sub>(BR)</sub> 1) 75			٧
•		4	ρF
O		•	•
		6	ns
π		J	,,,
		0.8 0.67 0.92 0.8 1.05 0.95 1.12	0.8 0.9 0.67 0.75 0.92 1.0 0.8 0.85 1.05 1.2 0.95 1.0 1.12 1.25 1.00 1.00 1.00 1.00 1.00 1.00 1.00 1.0

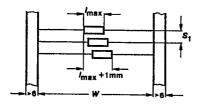
<sup>&</sup>lt;sup>1)</sup>  $\frac{t_p}{T}$  = 0.01,  $t_p$  = 0.3 ms

#### 8. Taped devices

#### 8.1. Tape specification for diodes and rectifiers with axial leads

T-91-20

Diodes and rectifiers with axial leads are normally delivered in taped form, according to IEC 286-1 (see Fig. 8.1). The cathode side is designated by a coloured tape. Tape devices are delivered either on reels (normal version), or on request folded in cartons (Ammopack). The GPS-version is normally delivered in Ammopack. Diodes in DO 35 package are also available as radial taped. For details please contact factory.



 $S_1 = 5 \pm 0.5$  for devices with diameter d < 4.5 mm

=  $10 \pm 0.5$  mm for devices with diameter d > 4.5 mm

 $W = 53 \pm 2$  mm for normal taped form

= 26 + 1.5 for GPS version

Allovable deviation above 10 taped steps  $\pm$  2 mm

Fig. 8.1 Standard taped diodes with axial leads

### 8.2. Tape specifications for Surface Mounted Devices (SMDs)

SMDs are delivered either bulk packed or taped on blister tape according to IEC 286-3. The mounting side is oriented to the bottom side of the tape.

For standard taping suffix "GS 08" is added to the type number.

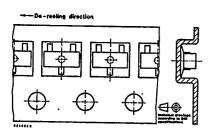


Fig. 8.2 Standard taped SOD 80

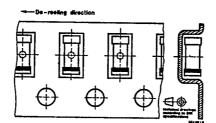


Fig. 8.3 Standard taped SOT 23

Fig. 8.4 Tape dimensions for SOD 80 in mm

Fig. 8.5 Tape dimensions for SOT 23 and SOT 143 in mm

Quantities per reel: SOD 80-2500 comp.

SOT 23-3000 comp.

SOT 143 - 3000 comp.

Missing devices:

Maximum of 0.5% of the total number of components per real may be missing exclusively missing components at the beginning and at the end of the real. Maximum of three consecutive components may be missing, provided this gap is followed by six consecutive components. See Fig. 8.6.

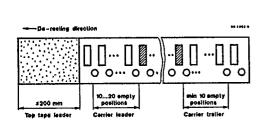


Fig. 8.6 Beginning and end of the reel

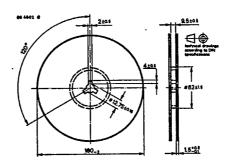


Fig. 8.7 Dimensions of the reel in mm